Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK2545

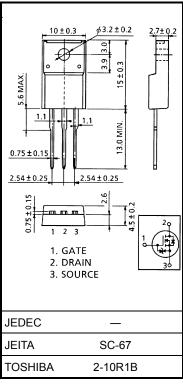
DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain-source ON resistance : RDS (ON) = $0.9 \Omega(\text{typ.})$ • High forward transfer admittance : $|Y_{fs}| = 5.5 \text{ S (typ.})$

• Low leakage current : $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 600 \text{ V)}$ • Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage (Ro	_{GS} = 20 kΩ)	V_{DGR}	600	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	I _D	6	Α
	Pulse (Note 1)	I _{DP}	24	Α
Drain power dissipation	n (Tc = 25°C)	P_{D}	40	W
Single pulse avalanche	e energy (Note 2)	EAS	345	mJ
Avalanche current		I _{AR}	6	Α
Repetitive avalanche e	nergy (Note 3)	E _{AR}	4	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 16.8 mH, R_G = 25 Ω , I_{AR} = 6 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.

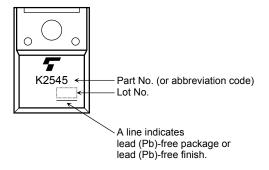
Electrical Characteristics (Ta = 25°C)

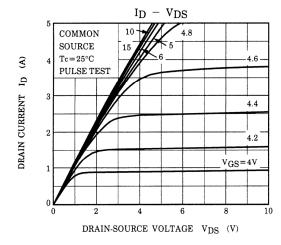
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{DS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	/oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3 A	_	0.9	1.25	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	2.0	5.5	_	S
Input capacitano	ce	C _{iss}		_	1300	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		Coss		_	400	_	
Switching time	Rise time	t _r	V _{GS} _{0V} I _D = 3A V _{out} R _L = 100Ω	_	25	_	
	Turn-on time	t _{on}		_	45	_	- ns
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	$V_{DD} \stackrel{\rightleftharpoons}{=} 300V$ Duty $\leq 1\%$, $t_w = 10 \mu s$	l	150	ı	
Total gate charge (Gate-source plus gate-drain)		Qg		_	30	_	
Gate-source charge		Qgs	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		18		nC
Gate-drain ("miller") charge		Q _{gd}			12	_	

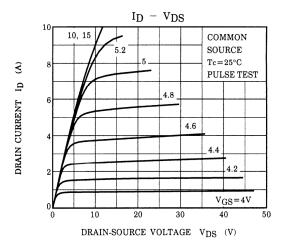
Source-Drain Ratings and Characteristics (Ta = 25°C)

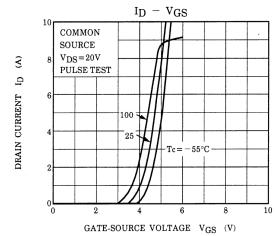
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	-	_	6	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 6 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 6 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	_	1000	_	ns
Reverse recovery charge	Qrr	10R - 0 A, VGS - 0 V, αιDR / αι - 100 A / μs		7.0	_	μC

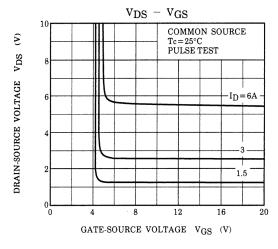
Marking

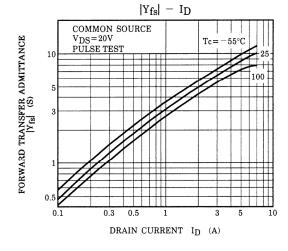


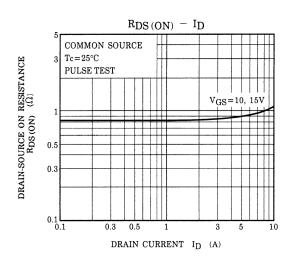




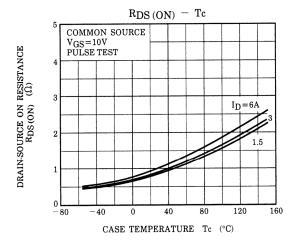


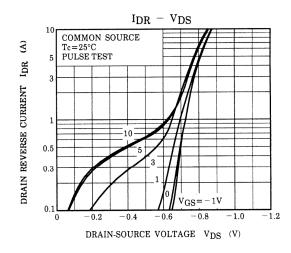


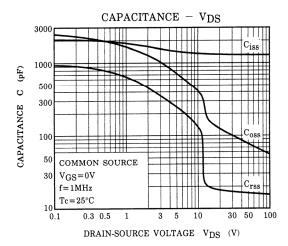


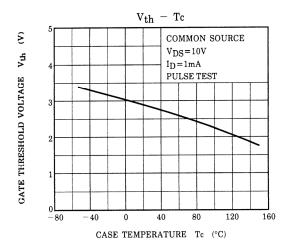


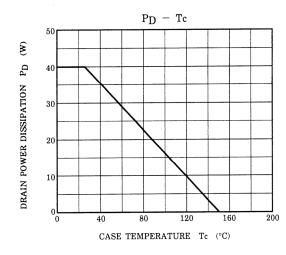
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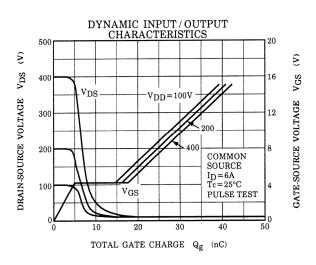


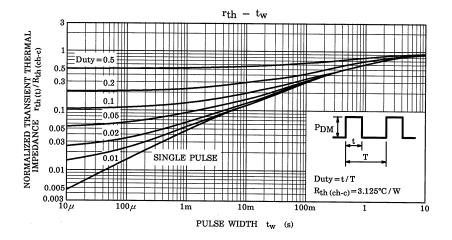


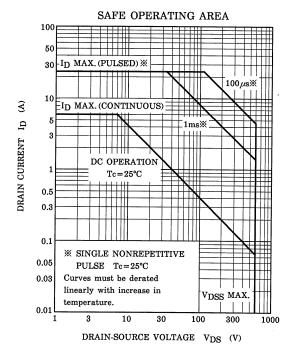


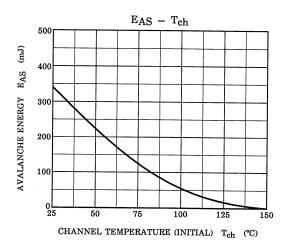


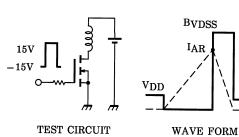












$$\begin{split} R_G &= 25~\Omega \\ V_{DD} &= 90~V,\, L = 16.8~mH \end{split}$$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

 v_{DS}

RESTRICTIONS ON PRODUCT USE

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